

L Number	Hits	Search Text	DB	Time stamp
97	26	((planar or flat\$4) and roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and metal and bond\$4 and mark	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 12:00
98	12	((planar or flat\$4) and roughn\$4) and (substrate near10 bond\$4 near10 mark) and metal	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/29 12:01
-	1	JP07145688.ap.	USPÄT; JPO	2003/12/30 11:43
-	1	JP06331208.ap.	USPAT; JPO	2003/12/26 13:30
-	1547	349/158	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/26 13:31
-	627	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/26 13:36
-	1	JP08216995.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/26 13:43
-	45	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal) and align\$4 and mark	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/26 13:52
-	181	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/28 16:05
-	95	349/113 and roughn\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/30 16:22
-	57	349/158 and roughn\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 16:55
-	20	process adj control adj mark	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 17:24
-	751	mean adj wavelength	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 17:25
-	5	(mean adj wavelength) and (average adj rough\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 17:26
-	55	(mean adj wavelength) and (liquid adj crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/29 17:35
-	1	6650395.pn.	USPAT	2003/12/29 17:35
-	4	("4693559"   "5724111"   "6061112"   "6331882").PN.	USPAT	2003/12/30 08:43

-	63	(seal near10 (flat or planar))and 349/\$.ccls.	USPAT; US-PGPUB; JPO	2003/12/30 14:15
-	0	(seal near10 (flat or planar))and 349/\$.ccls and rough\$4.	USPAT; US-PGPUB; JPO	2003/12/30 11:50
-	0	(seal near10 (flat or planar))and 349/\$.ccls and roughen\$4.	USPAT; US-PGPUB; JPO	2003/12/30 11:51
-	5	(seal near10 (flat or planar)) with roughen\$4	USPAT; US-PGPUB; JPO	2003/12/30 14:16
-	6	349/153 and (flat or planar) and roughen\$4	USPAT; US-PGPUB; JPO	2003/12/30 14:25
-	5953	seal\$4 and (flat or planar) and roughen\$4	USPAT; US-PGPUB; JPO	2003/12/30 14:25
-	0	(seal\$4 near10 (flat or planar)) and roughen\$4 and 349/\$ccls.	USPAT; US-PGPUB; JPO	2003/12/30 14:26
-	604	(seal\$4 near10 (flat or planar)) and roughen\$4	USPAT; US-PGPUB; JPO	2003/12/30 14:36
-	14	(seal\$4 near10 (flat or planar)) and roughen\$4 and 349/\$.ccls.	USPAT; US-PGPUB; JPO	2003/12/30 14:36
-	12	349/160 and roughn\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/30 16:22
-	15	349/67 and roughn\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/30 16:22
-	24	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal) and metal and (alignment adj mark)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 16:13
-	178	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and (liquid adj crystal) and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 16:42
-	3	((planar or flat\$4) near10 roughn\$4 near10 metal) and substrate and reflect\$4 and (liquid adj crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 16:20
-	21	((planar or flat\$4) near10 roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 16:46
-	1	((planar or flat\$4) and roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and (metal near10 mark)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/28 16:47
-	175	((planar or flat\$4) and roughn\$4) and substrate and reflect\$4 and 349/\$.ccls. and metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/29 11:59